

FPM 330X-UTG

Flex Process Module for manufacturing of flexible electronics by using ultra thin glass substrate:

Integration of all customer processes:

- atmosphere, inert/glovebox, vacuum
- thin film deposition, printing
- structuring, annealing
- laminating

LINEAR DEPOSITION SOURCE

Patented innovative evaporator design

- SCALABLE technology
- OPTIMAL temperature uniformity
- HIGH rate at low temperature
- EXCELLENT deposition uniformity
- COMPACT design
- EASE of operation

Discover the possibilities to build up new business segments!

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